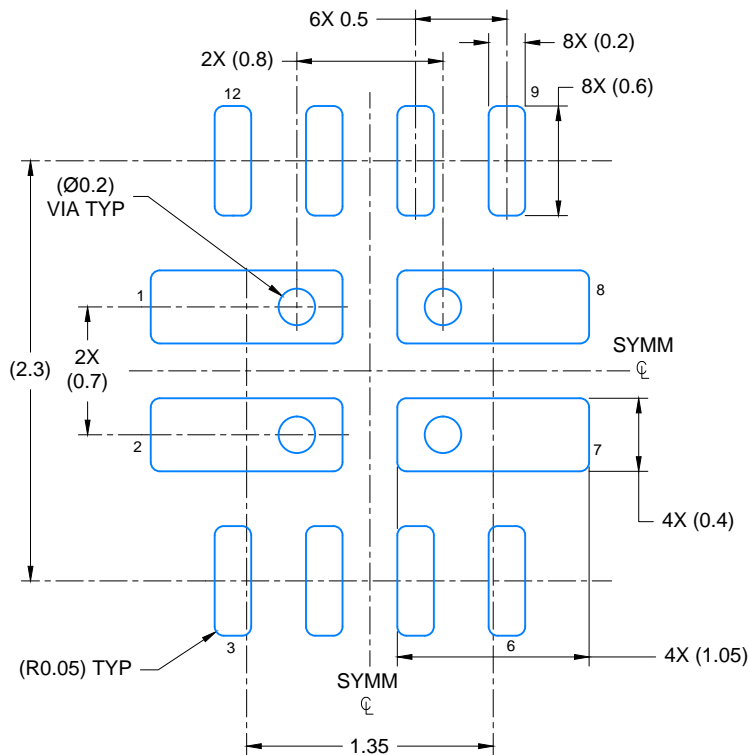


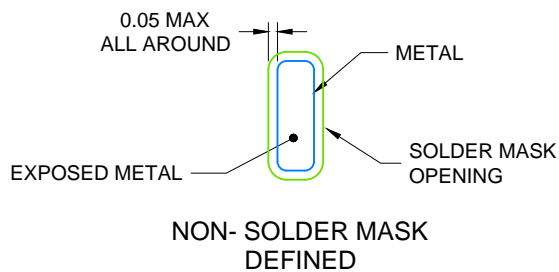
4224010/A 11/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



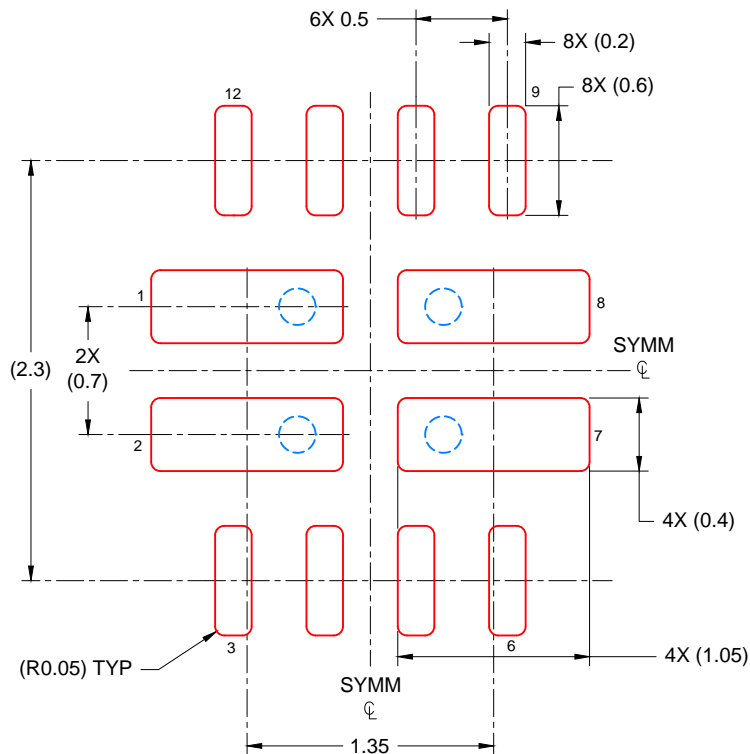
LAND PATTERN EXAMPLE  
SCALE: 25X



4224010/A 11/2017

NOTES: (continued)

- For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).



SOLDER PASTE EXAMPLE  
 BASED ON 0.1mm THICK STENCIL

EXPOSED PAD  
 100% PRINTED COVERAGE BY AREA  
 SCALE: 25X

4224010/A 11/2017

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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